APPLICA	BLE STAN	DARD									
	Operating Temperature R	ange	-55 °C to 85 °	·			•				
Rating	Voltage Current		50 V AC 0.7 A 1			rage Humidity Ra			Relative humidity 8	5% max	<
					Operating		Humidity Range		(Not dewed)		
			SPEC	IFIC/	ATION	IS					
IT	EM	TEST METHOD				REQUIREMENTS				QT	AT
CONSTRUCTION											
General Exa	mination	Visually and by measuring instrument.				According to drawing.				×	×
Marking		Confirmed visually.								×	×
	CHARAC										
Contact Resistance		100 mA(DC or 1000Hz)				70mΩ MAX.				×	↓ –
Insulation Resistance Voltage Proof		100 V DC. 150 V AC for 1 min.				100 M Ω MIN. No flashover or breakdown.				×	<u> </u>
	CAL CHAR					INO IIAS	novel of bi	eaku	OWII.	×	×
Insertion and			d by applicable connector.			Insertic	n Force:	62	2 N MAX.	Τ×	Т_
Withdrawal F		and a sy applicable conflicter.				Withdrawal Force: 6.2 N MIN.				^	
Mechanical Operation		50 times insertions and extractions.				① Contact Resistance : 80m Ω MAX.				×	-
						② No damage, crack and looseness of parts.					
Shock		Frequency 10 to 55 to 10Hz, approx 5min			 No electrical discontinuity of 1 μs. No damage, crack and looseness of parts. 				×	-	
		Single amplitude : 0.75 mm, 10 cycles for 3 axial directions.									
		490 m/s ² , duration of pulse 11 ms							×	 	
		at 3 time:	s for 3 both axial directions.								
	MENTAL C	HARAC	TERISTICS								
Damp Heat (Steady state)		Exposed at 40±2 °C, 90 ~ 95 %, 96 h.			 ① Contact Resistance : 80m Ω MAX. ② Insulation Resistance:100 MΩ MIN. 				×	-	
Rapid Change of		Temperature -55 → +85 °C			③ No	③ No damage, crack and looseness of parts.			×		
Temperature		Time	Time $30 \rightarrow 30$ min. under 5 cycles.								
			cycles. n time to chamber : within 2~3	MINI)							
Cold		Exposed at -55°C, 96 h			① Contact Resistance : 80m Ω ② No damage, crack and looseness of parts.				×	<u> </u>	
Dry Heat		Exposed at 85°C, 96 h							×	_	
Sulfur Dioxide		Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h.			No defect such as corrosion which impairs				+×	+-	
		(Test standard: JIS C 60068)				the function of connector.					
					② Contact Resistance : 80m Ω						
Resistance to Soldering Heat		1)Reflow soldering :				No deformation of case of excessive looseness of the terminal.				s ×	-
Soldering Heat		Peak TMP : 260°CMAX Reflow TMP: 220°CMIN for 60sec									
			ing irons : 360°C MAX. for 5	sec.							
		Soldered at solder temperature				A new uniform coating of solder shall cover a				×	1-
		245±3°C for immersion duration, 3 sec.			í\	minimum of 95 % of the surface being immersed.					
COUNT		DESCRIPTION OF REVISIONS D			DESIG	NED			CHECKED	TDA	ATE
2 1	· -					ASHIGE					10. 29
REMARKS ⁽¹⁾ Include temperature rise cau ⁽²⁾ "STORAGE" means a lor			re rise caused by current-carrying. neans a long-term storage state for the unused product				APPROVE	ΞDΪ	HS, OKAWA	_	09. 02
							CHECKE	.D	KN. SHIBUYA		09. 02
	before asse Decapitaliz	mbly to PCB.					DESIGNE	ED			11, 15
Unless oth			d, refer to JIS-C-5402.			DRAW		-	AH. EDASHIGE	+	11. 15
Note QT:Qualification Test AT:A						RAWING NO.			ELC4-352599-00		
								FX22-80P-0, 5SH			
HS.		PECIFICATION SHEET			PART NO. CODE NO.					\triangle	1/1
1 = = HIK		OSE ELECTRIC CO., LTD.			LCODE	INU.	⊢ ∪LO	CL572-3004-2-00 /2			